

L Number	Hits	Search Text	DB	Time stamp
1	341	"wedge bonding" and Al	USPAT; US-PGPUB	2001/12/17 09:07
2	273303	Cu or copper	USPAT; US-PGPUB	2001/12/17 09:07
4	178	("wedge bonding" and Al) and (Cu or copper)	USPAT; US-PGPUB	2001/12/17 09:08
5	13322	"bond pad" or "bonding pad"	USPAT; US-PGPUB	2001/12/17 09:09
6	114	(("wedge bonding" and Al) and (Cu or copper)) and ("bond pad" or "bonding pad")	USPAT; US-PGPUB	2001/12/17 09:09
7	46487	438/\$.ccls.	USPAT; US-PGPUB	2001/12/17 09:09
8	24	((("wedge bonding" and Al) and (Cu or copper)) and ("bond pad" or "bonding pad")) and 438/\$.ccls.	USPAT; US-PGPUB	2001/12/17 09:21
9	70141	Ta or tantalum	USPAT; US-PGPUB	2001/12/17 09:15
10	5	((("wedge bonding" and Al) and (Cu or copper)) and ("bond pad" or "bonding pad")) and 438/\$.ccls.) and (Ta or tantalum)	USPAT; US-PGPUB	2001/12/17 09:15
11	944441	heat\$	USPAT; US-PGPUB	2001/12/17 09:28
12	16	((("wedge bonding" and Al) and (Cu or copper)) and ("bond pad" or "bonding pad")) and 438/\$.ccls.) and heat\$	USPAT; US-PGPUB	2001/12/17 09:28
-	466	("438/612").CCLS.	USPAT; US-PGPUB	2001/12/14 09:45
-	263	(("438/612").CCLS.) and wire	USPAT; US-PGPUB	2001/12/14 09:46
-	249	((("438/612").CCLS.) and wire) and bond\$	USPAT; US-PGPUB	2001/12/14 14:21
-	314	438/614.cccls.	USPAT; US-PGPUB	2001/12/14 14:21
-	417196	wire	USPAT; US-PGPUB	2001/12/14 14:27
-	474449	bond\$	USPAT; US-PGPUB	2001/12/14 14:32
-	95777	wire and bond\$	USPAT; US-PGPUB	2001/12/14 14:32
-	132	438/614.cccls. and (wire and bond\$)	USPAT; US-PGPUB	2001/12/14 14:43
-	527	438/656.cccls.	USPAT; US-PGPUB	2001/12/14 14:43
-	30	(wire and bond\$) and 438/656.cccls.	USPAT; US-PGPUB	2001/12/14 14:46
-	153	438/661.cccls.	USPAT; US-PGPUB	2001/12/14 14:46
-	11	(wire and bond\$) and 438/661.cccls.	USPAT; US-PGPUB	2001/12/14 14:47
-	588	438/687	USPAT; US-PGPUB	2001/12/14 14:48
-	391	438/687.cccls.	USPAT; US-PGPUB	2001/12/14 14:48
-	31	(wire and bond\$) and 438/687.cccls.	USPAT; US-PGPUB	2001/12/14 14:51
-	386	438/688.cccls.	USPAT; US-PGPUB	2001/12/14 14:51
-	45	(wire and bond\$) and 438/688.cccls.	USPAT; US-PGPUB	2001/12/14 14:55
-	1431	438/for.343.cccls.	EPO; JPO; DERWENT	2001/12/14 14:55
-	50658	wire and bond\$	EPO; JPO; DERWENT	2001/12/14 14:56
-	111	438/for.343.cccls. and (wire and bond\$)	EPO; JPO; DERWENT	2001/12/14 15:02

	64179	interconnect	EPO; JPO; DERWENT	2001/12/14 14:58
	553	438/for.352.ccls.	EPO; JPO; DERWENT	2001/12/14 15:02
	7	(wire and bond\$) and 438/for.352.ccls.	EPO; JPO; DERWENT	2001/12/14 16:03
	7	(Ta and Cu and Al and TaAl) and wire and bond\$	USPAT; US-PGPUB	2001/12/14 16:05
	244548	semiconductor	USPAT; US-PGPUB	2001/12/14 16:05
	5	((Ta and Cu and Al and TaAl) and wire and bond\$) and semiconductor	USPAT; US-PGPUB	2001/12/14 17:45
	1	("5045151").PN.	USPAT; US-PGPUB	2001/12/14 17:46
	2	(("5719448") or ("5565378")).PN.	USPAT; US-PGPUB	2001/12/14 17:47
	0	("200100341").PN.	USPAT; US-PGPUB	2001/12/14 17:47
	1	("0034119").PN.	USPAT; US-PGPUB	2001/12/14 17:48
	0	("0034119").PN.	US-PGPUB	2001/12/14 17:48
	1	("20010034119").PN.	US-PGPUB	2001/12/14 17:49
	314	("438/614").CCLS.	USPAT; US-PGPUB	2001/12/14 17:50
	70020	Ta or tantalum	USPAT; US-PGPUB	2001/12/14 17:50
	31	(("438/614").CCLS.) and (Ta or tantalum)	USPAT; US-PGPUB	2001/12/14 17:58
	391	438/687.ccls.	USPAT; US-PGPUB	2001/12/14 17:58
	244	(Ta or tantalum) and 438/687.ccls.	USPAT; US-PGPUB	2001/12/14 18:24
	13286	"bond pad" or "bonding pad"	USPAT; US-PGPUB	2001/12/14 17:59
	14	((Ta or tantalum) and 438/687.ccls.) and ("bond pad" or "bonding pad")	USPAT; US-PGPUB	2001/12/14 18:01
	115	438/617.ccls.	USPAT; US-PGPUB	2001/12/14 18:01
	4	(Ta or tantalum) and 438/617.ccls.	USPAT; US-PGPUB	2001/12/14 18:01
	417196	wire	USPAT; US-PGPUB	2001/12/14 18:24
	54	((Ta or tantalum) and 438/687.ccls.) and wire	USPAT; US-PGPUB	2001/12/14 18:25
	44	((((Ta or tantalum) and 438/687.ccls.) and wire) not ("bond pad" or "bonding pad"))	USPAT; US-PGPUB	2001/12/17 09:07